



*From Nano to Micro Power Electronics
And Packaging Workshop
November 26th, 2026
Tours, France
16th Edition*



life.augmented

TECHNICAL PROGRAM

Technical Committee:

Daniel ALQUIER	TOURS University	France	Co-chairman
Laurent BARREAU	ST Microelectronics Tours	France	Chairman
Lars BOETTCHER	FRAUNHOFER Institute	Germany	
Cyril BUTTAY	AMPERE Laboratory	France	
Jean-Luc DIOT	PRIVATE	France	
Franck DOSSEUL	VERMON	France	Co-chairman
Guo-Quan LU	VIRGINIA TECH	USA	
Alexandre SEIGNEURIN	ST Microelectronics Tours	France	

8 h 30 Workshop package and badge distribution

Exhibition area opening :

KYOCERA, MICRONOR, SCHUNK, CCI EUROLAM, ZESTRON, METRONELEC, ACCELONIX, PROTAVIC, BESI

9 h 00 Welcome and workshop program presentation

9 h 15 Keynote: Packaging technology unlocks power density – Laurent Herard – ST Microelectronics, France

10 h 05 Session 1: Designs, Applications & Reliability

10h 05 Co-designed and co-packaged thermal solutions for advanced semiconductor packaging – Henry A. Martin – TNO, Netherlands

10 h 30 Coffee break / Table Top Exhibition and presentation

11 h 00 Session 1: Design, Applications & Reliability con't

11 h 00 Thermal packaging and direct cooling strategy for a high-power density hybrid GaN / SiC power converter – Ismael Aouichak – GREMAN University of Tours, France

11 h 25 Reliability of sintered power modules through surface treatment
Etienne Wortham – ZESTRON Europe, France

11 h 50 Numerical study of package wire bond strategy effects on power module current carrying capability – Mingyue Huang – ST Microelectronics Shenzhen, China

12 h 15 Table Top Exhibition visit and Lunch (Buffet)

13 h 30 Session 2: Materials, Processes and Technologies

- 13 h 30** A novel 50W/mK thermally conductive paste for power applications – David Oscar Vella – HENKEL AG, Germany
- 13 h 55** Third party reproducibility of 200°C pressure assisted silver sintering for power module attach on Ag plated heatsinks – Makoto Morohashi – NAMICS, Japan
- 14 h 20** Rheology meets precision – a rheological study on silver pressure sinter paste – Thorsten Vehoff – HERAEUS, Germany
- 14 h 45** Examining copper sinter as an interconnect material in power electronics assembly – the value propositions, the challenges and the target applications – Karthik Vijay – INDIUM Corporation, Great Britain

15 h 10 Coffee break / Table Top Exhibition

15 h 40 Session 2: Materials, Processes and Technologies con't

- 15 h 40** Development of sintered and semi sintered silver die attach adhesives for high thermal conductivity semiconductor packaging – Vincent Charlot - PROTAVIC, France
- 16 h 05** Large area silver sintering on aluminium graphite plates – a feasibility and reliability study for high-performance power modules – Klaus Hoell – SCHUNK, Austria
- 16 h 30** Enabling metallization free GaN die attach with high thermal conductivity silver adhesive – Jocelyn Leong - TANAKA, Germany

16 h 55 Closing

17 h 10 End of session

Social events:

- **visit of a wine cellar in Loire Valley. Departure from Greman's institute at 17h20**
Gaudrelle Castle
12 quai de la Loire, 37210 Rochecorbon



A typical troglodyte wine cellar

- **dinner in a gastronomic restaurant in Tours at 20h00**
La Chope
25bis avenue de Grammont TOURS



From Nano to Macro Power Electronics and Packaging European Workshop

Thursday, November 26th, 2026

GREMAN (ECOLE D'INGENIEURS POLYTECH TOURS)
Polytech - Bat E - 64 avenue Jean Portalis 37200 Tours
Amphitheater 3 of department électronique et énergie

Registration Form
Final registration Thursday November 26th, 2026

COMPANY:

NAME:

FIRSTNAME:

ADDRESS:

TEL:

E-MAIL:

→ Send back to IMAPS France by E-mail: imaps.france@orange.fr

FEES (including conferences attendance, table top visit, lunch, coffee breaks, social event and closing dinner)

Conferences on free access on website www.imapsfrance.org after the event.

- ☐ IMAPS MEMBER 200 € HT - 240 € TTC
- ☐ Non IMAPS MEMBER 260 € HT – 312 € TTC
- ☐ SPEAKERS/CHAIRS 130 € HT - 156 € TTC

For foreign companies, VAT is excluded

Do not forget to tick boxes if you want to participate to our social event

- Visit of a Touraine specific place (Thursday evening) ☐ yes ☐ no

- Dinner after the visit (Thursday evening) ☐ yes ☐ no

☐ **On line Payment and Registration available on** www.france.imapseurope.org

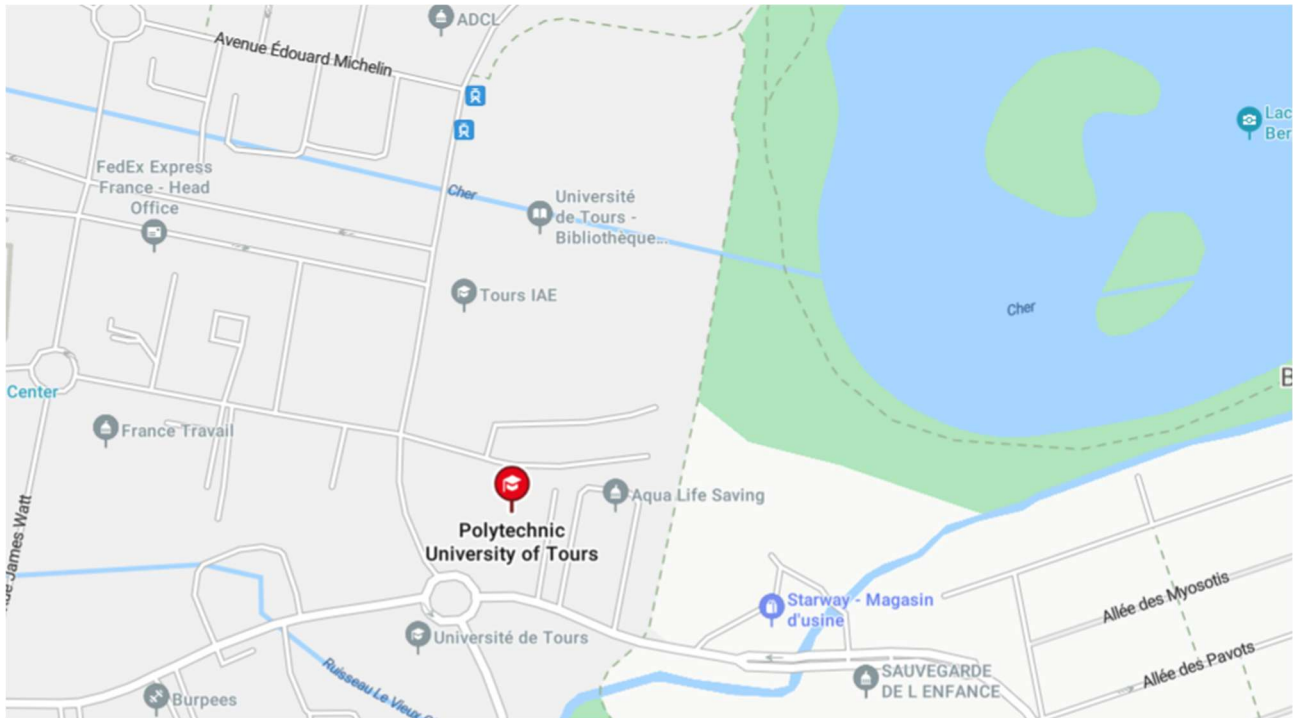
PAYMENT BANK REFERENCES

Credit card accepted, as well as payment by cheque or wire transfer.

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Email : imaps.france@orange.fr

How to reach GREMAN



Access by car from the A10 motorway

In the Paris-Bordeaux direction,

Take the exit n ° 22 Saint-Avertin, then follow the direction of the 2 Lions.

In the Bordeaux-Paris direction,

Take the exit n ° 23, follow the direction Tours-Center then the 2 Lions direction

Access by train and tram or bus

You can either go to the Tours train station which is in the city center or to the Saint Pierre des Corps railway station which is on the outskirts and which has both rail shuttles to Tours and buses to different points of the city. More info on the website of Fil Bleu.

Access to Polytech Tours by tramway line A : stop "Fac 2 Lions" .